Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: E = .0047” X .0047” B = .004” X .004”**

**Backside Potential: Collector**

**Mask Ref: CP716**

**APPROVED BY: DK DIE SIZE .020” X .020” DATE: 10/4/21**

**MFG: CENTRAL SEMI THICKNESS .009” P/N: 2N3635**

**DG 10.1.2**

#### Rev B, 7/19/02